

Features

- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish — NiPdAu Over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)



Bottom View

Ordering Information (Note 3)

| Part Number | Case | Packaging |
|--------------------|--------------|--------------------|
| (Type Number)-7* | X1-DFN1006-2 | 3,000/Tape & Reel |
| (Type Number)-7B** | X1-DFN1006-2 | 10,000/Tape & Reel |

*Add "-7" to the appropriate type number in Electrical Characteristics Table. Example: 6.2V Zener = BZT52C6V2LP-7.

**Add "-7B" to the appropriate type number in Electrical Characteristics Table. Example: 6.2V Zener = BZT52C6V2LP-7B.

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

BZT52CxxLP-7B



Top View
Bar Denotes
Cathode Side

BZT52CxxLP-7



Top View
Dot Denotes
Cathode Side

xx = Product Type Marking Code

Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|--------------------------|----------------|-------|------|
| Forward Voltage (Note 4) | V _F | 0.9 | V |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) T _A = 25°C | P _D | 250 | mW |
| Thermal Resistance, Junction to Ambient Air (Note 5) T _A = 25°C | R _{θJA} | 500 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

Electrical Characteristics @T_A = 25°C unless otherwise specified

| Type Number | Marking Code | Zener Voltage Range (Note 4) | | | | Maximum Zener Impedance f = 1kHz | | | Maximum Reverse Current (Note 4) | | Typical Temperature Coefficient @ I _{ZTC} | | Test Current I _{ZTC} |
|-------------|--------------|----------------------------------|---------|---------|-----------------|-----------------------------------|-----------------------------------|-----------------|----------------------------------|------------------|--|------|-------------------------------|
| | | V _Z @ I _{ZT} | | | I _{ZT} | Z _{ZT} @ I _{ZT} | Z _{ZK} @ I _{ZK} | I _{ZK} | I _R | @ V _R | Min | Max | |
| | | Nom (V) | Min (V) | Max (V) | | | | | | | | | |
| BZT52C2V4LP | WX | 2.4 | 2.20 | 2.60 | 5 | 100 | 600 | 1.0 | 50 | 1.0 | -3.5 | 0 | 5 |
| BZT52C2V7LP | W1 | 2.7 | 2.5 | 2.9 | 5 | 100 | 600 | 1.0 | 20 | 1.0 | -3.5 | 0 | 5 |
| BZT52C3V0LP | W2 | 3.0 | 2.8 | 3.2 | 5 | 95 | 600 | 1.0 | 10 | 1.0 | -3.5 | 0 | 5 |
| BZT52C3V3LP | W3 | 3.3 | 3.1 | 3.5 | 5 | 95 | 600 | 1.0 | 5 | 1.0 | -3.5 | 0 | 5 |
| BZT52C3V6LP | W4 | 3.6 | 3.4 | 3.8 | 5 | 90 | 600 | 1.0 | 5 | 1.0 | -3.5 | 0 | 5 |
| BZT52C3V9LP | W5 | 3.9 | 3.7 | 4.1 | 5 | 90 | 600 | 1.0 | 3 | 1.0 | -3.5 | 0 | 5 |
| BZT52C4V3LP | W6 | 4.3 | 4.0 | 4.6 | 5 | 90 | 600 | 1.0 | 3 | 1.0 | -3.5 | 0 | 5 |
| BZT52C4V7LP | W7 | 4.7 | 4.4 | 5.0 | 5 | 80 | 500 | 1.0 | 3 | 2.0 | -3.5 | 0.2 | 5 |
| BZT52C5V1LP | 9Y | 5.1 | 4.8 | 5.4 | 5 | 60 | 480 | 1.0 | 2.0 | 2.0 | -2.7 | 1.2 | 5 |
| BZT52C5V6LP | 9A | 5.6 | 5.2 | 6.0 | 5 | 40 | 400 | 1.0 | 1.0 | 2.0 | -2 | 2.5 | 5 |
| BZT52C6V2LP | 9B | 6.2 | 5.8 | 6.6 | 5 | 10 | 150 | 1.0 | 3.0 | 4.0 | 0.4 | 3.7 | 5 |
| BZT52C6V8LP | 9C | 6.8 | 6.4 | 7.2 | 5 | 15 | 80 | 1.0 | 2.0 | 4.0 | 1.2 | 4.5 | 5 |
| BZT52C7V5LP | 9D | 7.5 | 7.0 | 7.9 | 5 | 15 | 80 | 1.0 | 1.0 | 5.0 | 2.5 | 5.3 | 5 |
| BZT52C8V2LP | 9E | 8.2 | 7.7 | 8.7 | 5 | 15 | 80 | 1.0 | 0.7 | 5.0 | 3.2 | 6.2 | 5 |
| BZT52C9V1LP | 9F | 9.1 | 8.5 | 9.6 | 5 | 15 | 100 | 1.0 | 0.5 | 6.0 | 3.8 | 7.0 | 5 |
| BZT52C10LP | 9G | 10 | 9.4 | 10.6 | 5 | 20 | 150 | 1.0 | 0.2 | 7.0 | 4.5 | 8.0 | 5 |
| BZT52C11LP | 9H | 11 | 10.4 | 11.6 | 5 | 20 | 150 | 1.0 | 0.1 | 8.0 | 5.4 | 9.0 | 5 |
| BZT52C12LP | 9J | 12 | 11.4 | 12.7 | 5 | 25 | 150 | 1.0 | 0.1 | 8.0 | 6.0 | 10.0 | 5 |
| BZT52C13LP | 9K | 13 | 12.4 | 14.1 | 5 | 30 | 170 | 1.0 | 0.1 | 8.0 | 7.0 | 11.0 | 5 |
| BZT52C15LP | 9L | 15 | 13.8 | 15.6 | 5 | 30 | 200 | 1.0 | 0.1 | 10.5 | 9.2 | 13.0 | 5 |
| BZT52C16LP | 9M | 16 | 15.3 | 17.1 | 5 | 40 | 200 | 1.0 | 0.1 | 11.2 | 10.4 | 14.0 | 5 |
| BZT52C18LP | 9N | 18 | 16.8 | 19.1 | 5 | 45 | 225 | 1.0 | 0.1 | 12.6 | 12.4 | 16.0 | 5 |
| BZT52C20LP | 9P | 20 | 18.8 | 21.2 | 5 | 55 | 225 | 1.0 | 0.1 | 14.0 | 14.4 | 18.0 | 5 |
| BZT52C22LP | 9R | 22 | 20.8 | 23.3 | 5 | 55 | 250 | 1.0 | 0.1 | 15.4 | 16.4 | 20.0 | 5 |
| BZT52C24LP | 9S | 24 | 22.8 | 25.6 | 5 | 70 | 250 | 1.0 | 0.1 | 16.8 | 18.4 | 22.0 | 5 |
| BZT52C36LP | 9W | 36 | 34.0 | 38.0 | 2 | 90 | 350 | 0.5 | 0.1 | 25.2 | 36.5 | 45.5 | 5 |
| BZT52C39LP | 9X | 39 | 37.0 | 41.0 | 2 | 130 | 350 | 0.5 | 0.1 | 27.3 | 36.8 | 49.8 | 5 |

- Notes:
4. Short duration pulse test used to minimize self-heating effect.
 5. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at <http://www.diodes.com>.

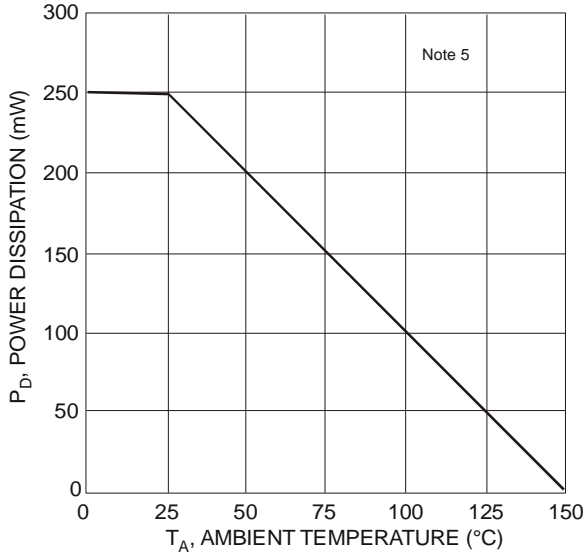


Fig. 1 Power Derating Curve

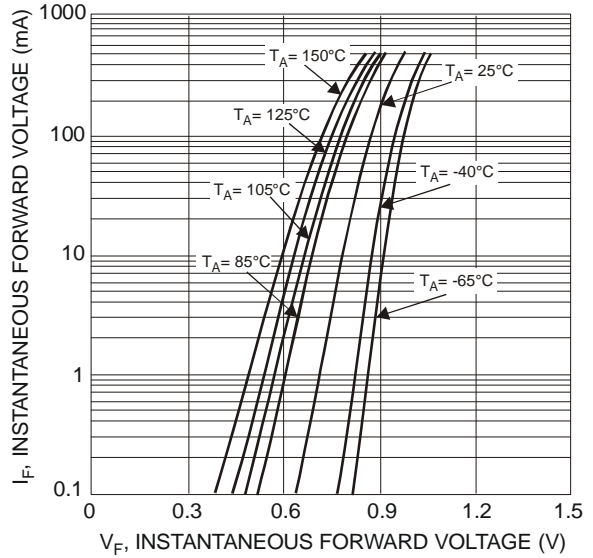


Fig. 2 Typical Forward Characteristics

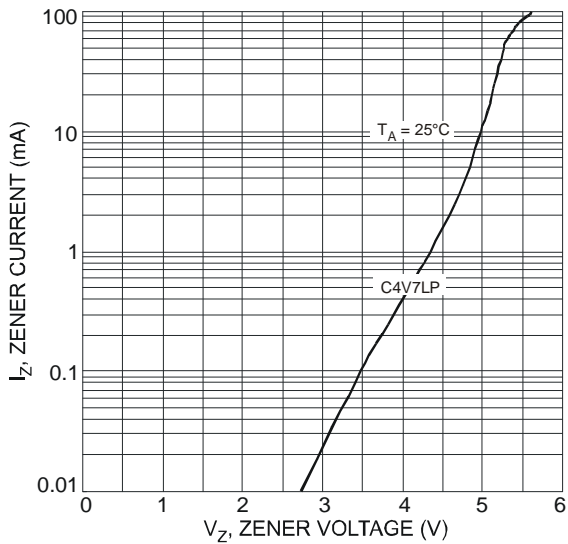


Fig. 3 Typical Reverse Characteristics

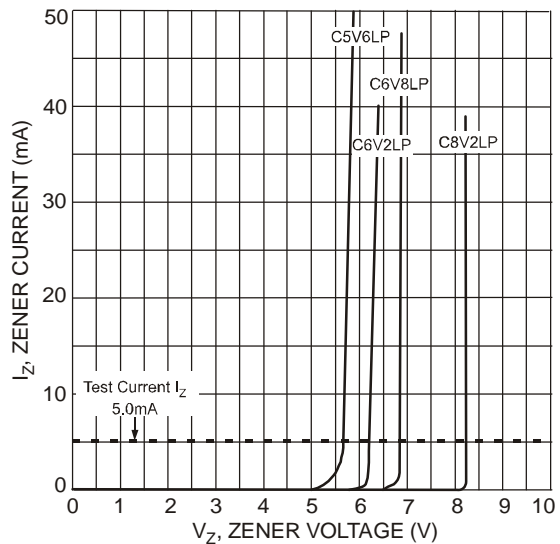


Fig. 4 Typical Zener Breakdown Characteristics

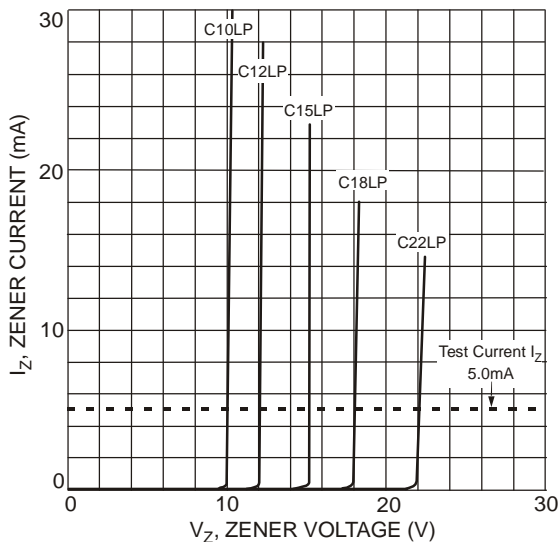


Fig. 5 Typical Zener Breakdown Characteristics

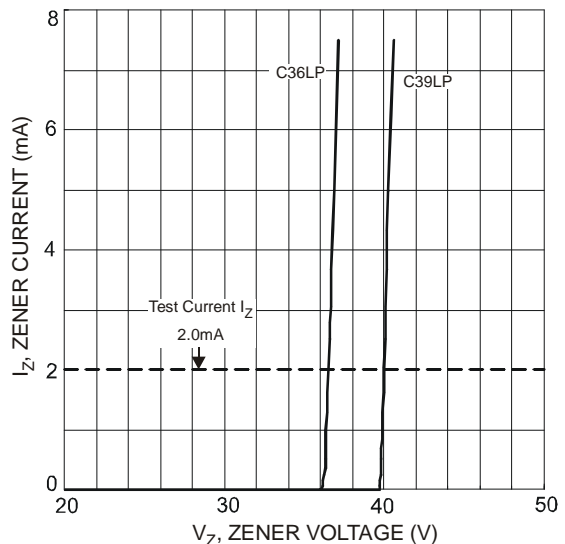
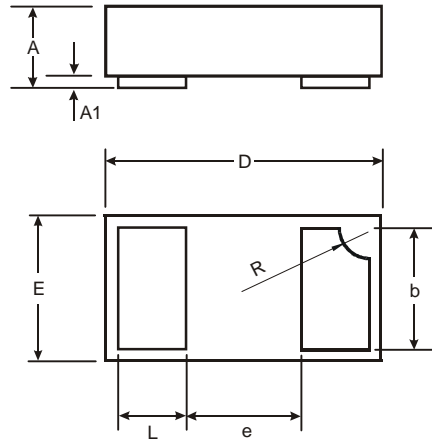


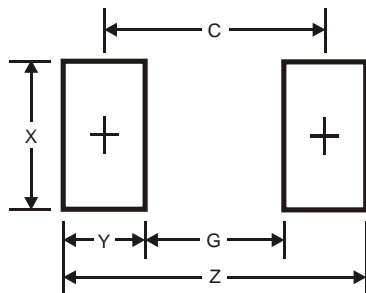
Fig. 6 Typical Zener Breakdown Characteristics

Package Outline Dimensions



| X1-DFN1006-2 | | | |
|----------------------|------|-------|------|
| Dim | Min | Max | Typ |
| A | 0.47 | 0.53 | 0.50 |
| A1 | 0 | 0.05 | 0.03 |
| b | 0.45 | 0.55 | 0.50 |
| D | 0.95 | 1.075 | 1.00 |
| E | 0.55 | 0.675 | 0.60 |
| e | - | - | 0.40 |
| L | 0.20 | 0.30 | 0.25 |
| R | 0.05 | 0.15 | 0.10 |
| All Dimensions in mm | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 1.1 |
| G | 0.3 |
| X | 0.7 |
| Y | 0.4 |
| C | 0.7 |

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